

# N-Channel Super Junction Power MOSFET III

## **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent Rds(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

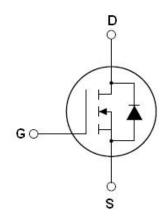
#### **Features**

- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V <sub>DS</sub>	700	V
R <sub>DS(ON)TYP</sub> .	1100	mΩ
$I_D$	4	A



Schematic diagram

## **Package Marking And Ordering Information**

Device	Device Package	Marking	
NCE70T1K2R	SOT-223-2L	NCE70T1K2R	



SOT-223-2L

Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (Vgs=0V)	V <sub>DS</sub>	700	V
Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V)	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	4	Α
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	2.5	Α
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	16	А
Maximum Power Dissipation(Tc=25℃)	$P_{D}$	5.2	W
Single pulse avalanche energy (Note2)	Eas	27	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AS</sub>	0.7	Α
Repetitive Avalanche energy $, t_{AR}$ limited by $T_{jmax}$	E <sub>AR</sub>	0.1	mJ



(Note 1)			
Parameter	Symbol	Value	Unit
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55+150	°C

### **Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	24	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Table 3. Liectrical orial acteristics (TA-23 Culliess otherwise noted)						
Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	700			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =700V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =700V,V <sub>GS</sub> =0V			50	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	3		4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =2A		1100	1300	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>lss</sub>	\/ -50\/\/ -0\/		304	350	PF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1.0MHz		17		PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.UMHZ		0.5		PF
Total Gate Charge	Qg	\/ -400\/   -40		8.8	12	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =480V, $I_{D}$ =4A, $V_{GS}$ =10V		2.3		nC
Gate-Drain Charge	Q <sub>gd</sub>	VGS-1UV		4		nC
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			8		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =380V, $I_{D}$ =2.5A,		4		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=5\Omega,V_{GS}=10V$		52	70	nS
Turn-Off Fall Time	t <sub>f</sub>			9	18	nS
Source- Drain Diode Characteristics			•			
Source-drain current(Body Diode)	I <sub>SD</sub>	T 05°0			4	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			16	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =4A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			200		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I <sub>F</sub> =2A,di/dt=100A/µs		0.6		uC
Peak reverse recovery current	I <sub>rrm</sub>			6		Α

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R<sub>G</sub>=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

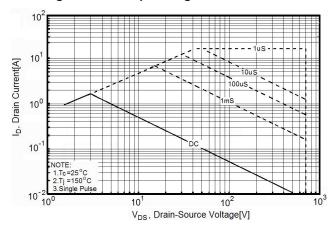


Figure 2. Source-Drain Diode Forward Voltage

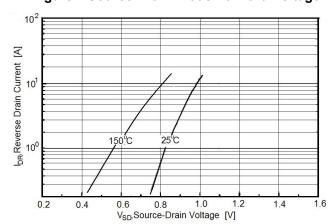


Figure 3. Output characteristics

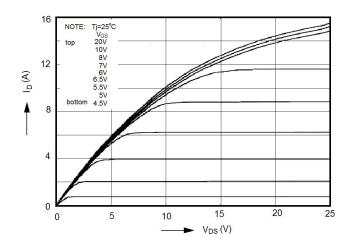


Figure 4. Transfer characteristics

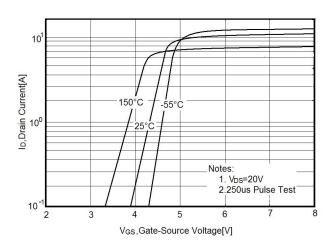


Figure 5. Static drain-source on resistance

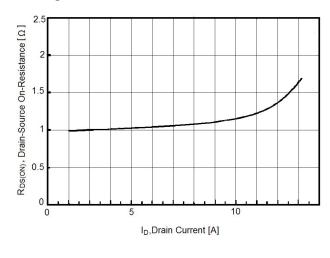


Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature

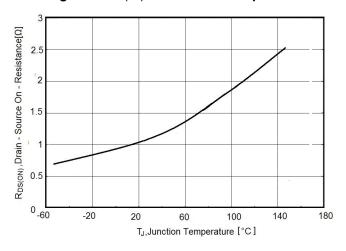




Figure 7. BV<sub>DSS</sub> vs Junction Temperature

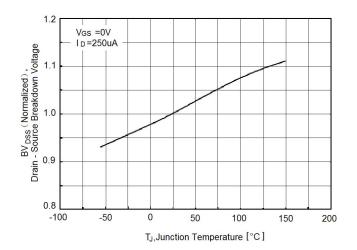


Figure 8. Maximum  $I_{\text{D}}$  vs Junction Temperature

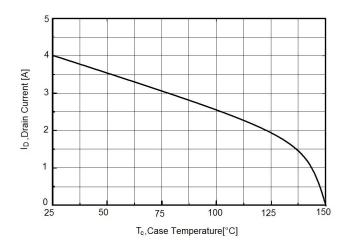


Figure 9. Gate charge waveforms

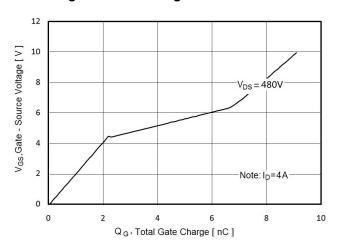


Figure 10. Capacitance

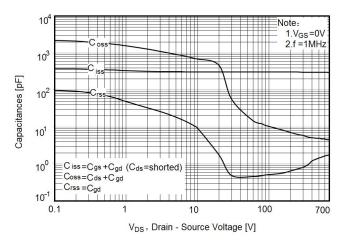
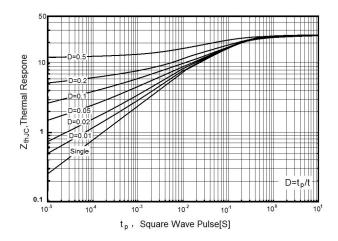


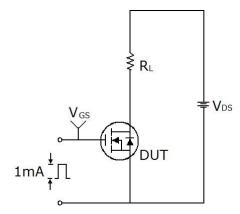
Figure 11. Transient Thermal Impedance

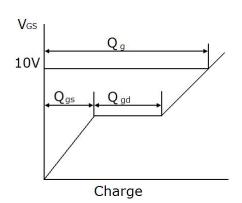




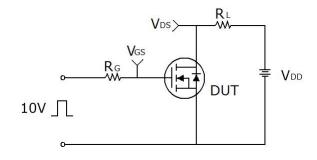
# **Test circuit**

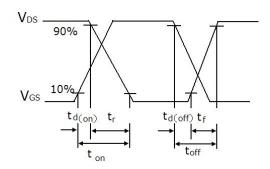
## 1) Gate charge test circuit & Waveform



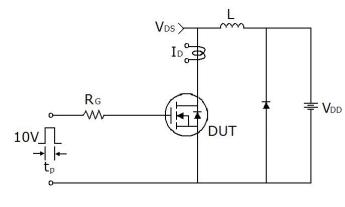


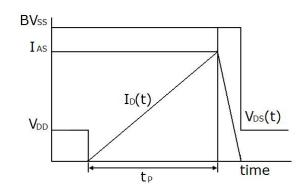
# 2) Switch Time Test Circuit:





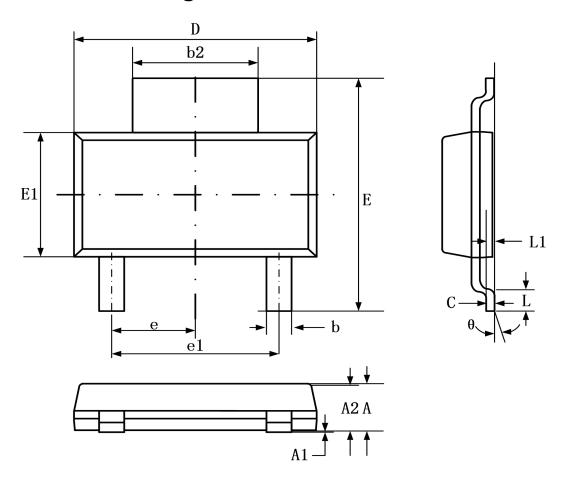
## 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **SOT-223-2L-B Package Information**



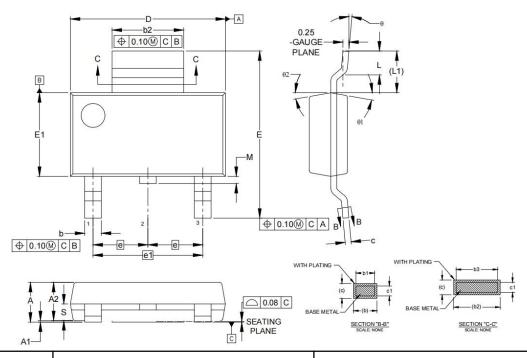
Symbol	Dimensions I	In Millimeters	Dimensions In Inches		
Cymbol	Min.	Max.	Min.	Max.	
A		1.80		0.071	
A1	0.02	0.10	0.001	0.004	
A2	1.50	1.70	0.059	0.067	
b	0.66	0.84	0.026	0.033	
b2	2.90	3.10	0.114	0.122	
С	0.23	0.35	0.009	0.014	
D	6.30	6.70	0.248	0.264	
E	6.70	7.30	0.264	0.287	
E1	3.30	3.70	0.130	0.146	
е	2.30	2.30 BSC.		0.091 BSC.	
e1	4.60 BSC.		0.182 BSC.		
L	0.81		0.032		
L1	0.25	0.25 BSC.		BSC.	
θ	0°	10°	0°	10°	

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V1.1



# **SOT-223-2L-J Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	1.52	1.80	0.060	0.071	
A1	0.02	0.10	0.001	0.004	
A2	1.50	1.70	0.059	0.067	
b	0.60	0.80	0.024	0.031	
b1	0.60	0.78	0.024	0.031	
b2	2.95	3.10	0.116	0.122	
b3	2.95	3.05	0.116	0.120	
С	0.24	0.32	0.009	0.013	
c1	0.24	0.30	0.009	0.012	
D	6.30	6.70	0.248	0.264	
E	6.70	7.30	0.264	0.287	
E1	3.30	3.70	0.130	0.146	
е	2.30	BSC.	0.091 BSC.		
e1	4.60	4.60 BSC.		0.182 BSC.	
L	0.90	1.10	0.035	0.043	
L1	1.75 REF		0.069 REF		
M		0.50		0.020	
S	0.70 REF		0.028 REF		
θ	0°	10°	0°	10°	
θ1	10° REF		10° REF		
θ2	10° REF		10° REF		



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